

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	33755	((substrate\$1 or wafer\$1) same (resist\$4)) and (electron\$1) and vacuum	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 10:57
L4	23851	3 and (((substrate\$1 or wafer\$1) same ((film\$1 or coat\$4 or pattern\$4 or layer\$1) with resist\$4)) and (electron\$1) and vacuum)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 10:58
L5	14536	4 and (((substrate\$1 or wafer\$1) same ((film\$1 or coat\$4 or pattern\$4 or layer\$1) with resist\$4)) and (electron\$1 with (beam\$1 or ray or irradiat\$4 or radiat\$4 or expos\$4 or impact\$4 or strik\$4)) and vacuum)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 11:00
L6	4104	5 and (((substrate\$1 or wafer\$1) same ((film\$1 or coat\$4 or pattern\$4 or layer\$1) with resist\$4)) same (electron\$1 with (beam\$1 or ray or irradiat\$4 or radiat\$4 or expos\$4 or impact\$4 or strik\$4)) and vacuum)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 11:00
L7	1151	6 and (((substrate\$1 or wafer\$1) same ((film\$1 or coat\$4 or pattern\$4 or layer\$1) with resist\$4)) same (electron\$1 with (beam\$1 or ray or irradiat\$4 or radiat\$4 or expos\$4 or impact\$4 or strik\$4)) same vacuum)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 11:01
L8	345	7 and (((substrate\$1 or wafer\$1) same ((film\$1 or coat\$4 or pattern\$4 or layer\$1) with resist\$4)) same (electron\$1 with (beam\$1 or ray or irradiat\$4 or radiat\$4 or expos\$4 or impact\$4 or strik\$4)) same vacuum) and (absorpt\$4 or collect\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 11:01
L9	75	8 and (((substrate\$1 or wafer\$1) same ((film\$1 or coat\$4 or pattern\$4 or layer\$1) with resist\$4)) same (electron\$1 with (beam\$1 or ray or irradiat\$4 or radiat\$4 or expos\$4 or impact\$4 or strik\$4)) same vacuum) and (absorpt\$4 and collect\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 11:06

L10	2	9 and (((substrate\$1 or wafer\$1) same ((film\$1 or coat\$4 or pattern\$4 or layer\$1) with resist\$4)) same (electron\$1 with (beam\$1 or ray or irradiat\$4 or radiat\$4 or expos\$4 or impact\$4 or strik\$4)) same vacuum) and ((absorpt\$4 and collect\$4) same carbon)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 11:02
L11	10	9 and (((substrate\$1 or wafer\$1) same ((film\$1 or coat\$4 or pattern\$4 or layer\$1) with resist\$4)) same (electron\$1 with (beam\$1 or ray or irradiat\$4 or radiat\$4 or expos\$4 or impact\$4 or strik\$4)) same vacuum) and (absorpt\$4 same carbon)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 11:04
L12	73	9 not 10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 11:04
L13	65	9 not 11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 11:04
L14	270	8 not 9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 11:06
L15	168	14 and absorpt\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 11:11
L16	20	15 and "250"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 11:09
L18	2	15 and "134"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 11:10
L19	93	15 and (absorpt\$4 and carbon)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 11:11

L20	27	19 and (absorpt\$4 same carbon)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 11:12
L21	66	19 not 20	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 11:14
L22	75	15 not 19	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 11:26
L23	4	("4342917").PN. OR ("4453262"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/13 11:19
L24	9	("3742229" "3742230" "3743842" "4035522" "4061829" "4215192").PN. OR ("4342917").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/13 11:20
L25	102	14 not 15	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 11:26
L26	32	25 and lithography	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 11:30
L27	70	25 not 26	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/13 11:30